

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	AIGBE40N65F5	**Issued**	08. April 2022
MA#	MA005710438		
Package	PG-TO263-7-11	**Weight***	1555.29 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.137	0.14	0.14	1374	1374
leadframe	inorganic material	phosphorus	7723-14-0	0.257	0.02		165	
	non noble metal	iron	7439-89-6	0.856	0.06		550	
	non noble metal	copper	7440-50-8	854.720	54.95	55.03	549556	550271
wire	non noble metal	aluminium	7429-90-5	7.784	0.50	0.50	5005	5005
encapsulation	inorganic material	zincoxide	1314-13-2	5.702	0.37		3666	
	miscellaneous	miscellaneous	-	22.808	1.47		14665	
	plastics	epoxy resin	-	85.531	5.50		54993	
	inorganic material	silicondioxide	60676-86-0	456.165	29.33	36.67	293298	366622
leadfinish	non noble metal	tin	7440-31-5	9.890	0.64	0.64	6359	6359
plating	inorganic material	phosphorus	7723-14-0	0.010			7	
	non noble metal	nickel	7440-02-0	4.272	0.27	0.27	2747	2754
solder	non noble metal	tin	7440-31-5	0.053			34	
	noble metal	silver	7440-22-4	0.066			43	
	non noble metal	lead	7439-92-1	2.531	0.16	0.16	1627	1704
heatspreader	inorganic material	phosphorus	7723-14-0	0.031			20	
	non noble metal	iron	7439-89-6	0.103	0.01		66	
	non noble metal	copper	7440-50-8	102.377	6.58	6.59	65825	65911
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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